| Part Number | USB3076 | | Rev | | С | Date | 16/11/11 |
|------------------------|--|----------|-----|---------|----|----------|----------|
| Product Description | Micro USB Receptacle, Type B, 5 Pin, SMT, Horizontal, Bottom Mount, without Peg, with Outer Shell Stakes, without Lead In | | | | | Page | 1 |
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|------------------------|------------------|---------------------------------------|------------|-------------|----------|----------------|-----------|---------|
| Product Description | | Receptacle, 1 out Peg, with | | | | | Page | 2 |
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| 1.0 SCOPE. | | | | | | | | |
| | | vers performa 6 (Type B, 5-P | | | requirem | ents for the N | Micro USB | |
| 2.0 PRODU | CT NAME AN | ID PART NUI | MBER. | | | | | |
| Micro | USB Recepta | cle, 5 Pin, Type | e B: USB3 | 076. | | | | |
| 3.0 PRODU | CT SHAPE, [| DIMENSIONS | S AND MA | TERIAL. | | | | |
| Pleas | e refer to draw | /ings. | | | | | | |
| 4.0 RATING | S. | | | | | | | |
| 4.1 Cu | rrent rating: Si | ignal (Pins 2, 3 | , 4) 1.0 | A | | | | |
| | P | ower (Pins1, 5 |) 1.8 | BA | | | | |
| 4.2 Vo | tage rating | | 30 | V AC | | | | |
| 4.3 Op | erating Tempe | erature Range | 30 | °C to +85°C | 2 | | | |
| 5.0 TEST AN | ND MEASUR | EMENT CON | IDITIONS | i. | | | | |
| specifi | | to meet electric oh 6.0. All tests | | | | | | ments |
| 6.0 PERFOR | MANCE. | | | | | | | |
| I | tem | Т | est Condit | tion | | Requi | irement | |
| | | | | | | | | |

| nem | Test Condition | Requirement | |
|------------------------|--|---|--|
| Examination of Product | Visual, dimensional and functional inspection as per quality plan. | Product shall meet requirements of product drawing and specification. | |
| | | | |
| | | | |



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6.1 Electrical Performance.

| Item | Test Condition | Requirement | |
|--|---|---------------|--|
| Low-signal Level Contact Resistance | Mate connectors, measure by dry circuit, 20 mV Max. In accordance with EIA-364-23. | 30 mΩ Max. | |
| Insulation Resistance | Mate/Un-mate connectors, apply 100V DC for 1 minute at sea level between adjacent terminal or ground. In accordance with EIA-364-21. | 1000 MΩ Min. | |
| Dielectric Strength | Mate/Un-mate connectors, apply 100V AC for 1 minute at sea level. In accordance with EIA-364-20. | No Breakdown. | |

6.2 Mechanical Performance.

| Item | Test Condition | Requirement |
|-------------------------------------|--|---|
| Mating/Un-mating Force (initial) | Mate/Un-mated at a rate of 12.5mm/min. In accordance with EIA-364-13. | Mating force: 35N Max. Un-Mating force: 8N Min. to 25N Max. |
| Durability | Cycle rate, 500 cycles per hour if done automatically and 200 if manual cycles. In accordance with EIA-364-09. | 10,000 cycles. Low Level Contact Resistance: 30mΩ Max. |
| Vibration | Mate connectors and subject to 5.35 Gs RMS. For a period of 15 minutes in each of the 3 mutually perpendicular axes. In accordance with EIA-364-28 Test condition V test letter A. | Appearance: No Damage. Contact Resistance: 50 mΩ Max. Discontinuity: 1.0 μ second Max. |
| Mechanical Shock | Mate connectors and subject to the following shock conditions, 3 shocks shall be applied along 3 mutually perpendicular axis, passing 100 mA current during the test. (Total of 18 shocks) Test Pulse: Half Sine Peak Value: 294 m/s ² (30G) Duration: 11ms. In accordance with EIA-364-27. Test condition H. | Appearance: No Damage. Contact Resistance: 10 mΩ Max. change allowed. Discontinuity: 1.0 μ second Max. |



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6.3 Environmental Performance and Others.

| Item | Test Condition | Requirement |
|--|---|--|
| Humidity Test | Subject mated connectors to Duration: 168 hours temperature between -25°C to +65°C with 90 to 95% RH. In accordance with EIA-364-31. Test condition A method III | Appearance: No Damage. Contact Resistance: 10 mΩ Max. change allowed. Insulation Resistance: 1000 MΩ Min. Dielectric Strength: No Breakdown |
| Salt Spray | Subject mated/unmated connectors to 5% salt-solution concentration, 35°C for 48 hours. In accordance with EIA-364-26, Test Condition B. | Low Level Contact Resistance: 50mΩ Max. No visible rust |
| Temperature Life | Subject mated connectors to temperature life at +85°C for 96hours. In accordance with EIA-364-17. Test condition 2 Method A. | Contact Resistance: 10 mΩ Max. change allowed. Insulation Resist.: 1000 MΩ Min. Shall meet visual requirement and show no physical damage. |
| Temperature Rise | Mate connector and measure the temperature rise of contact when the maximum rated current is passed and in accordance with EIA-364-70. | +30°C Max. change allowed. |
| Thermal Shock | Mate module and subject to follow condition for 10 cycles. At -55°C to +85°C. In accordance with EIA-364-32, test condition I. | No Damage 10mΩ Max. change allowed. Insulation Resist: 1000 MΩ Min. Dielectric Strength: No Breakdown |
| Solderability | Dip solder-tails in flux then immerse in solder bath at 245 ±5°C up to 0.5mm from the bottom of the housing for 4~5 seconds. In accordance with EIA-364-52, category 2. | 95% of immersed area must show no voids, pin holes. |
| Resistance to Soldering Heat (Reflow Soldering) | Sample mounted on PCB and subject to solder bath method, Temperature:260°C for 10±1 sec (High Temp. Thermoplastic). In accordance with EIA-364-56. | Without deformation of shell or excessive looseness of the terminals (pin.) |
| Resistance to Soldering Heat (Hand Soldering) | Sample mounted on PCB and subject to hand iron soldering, Temperature:350±10°C for 3±1 sec (High Temp. Thermoplastic). | Without deformation of shell or excessive looseness of the terminals (pin.) |



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7.0 RESISTANCE TO INFRARED REFLOW SOLDERING HEAT 7.1 Lead Free Process: Reflow soldering cycles limited to two times Temp 260°C **TEMPERATURE ON BOARD PATTERN SIDE** Peak temp 260°C MAX.(10sec. Max) 200°C Min 40 sec. Min Slope <3°C/Sec 230°C Min Pre-heat Hold time for 150~180°C Max. is 60~120sec. 8.0 PRODUCT QUALIFICATION AND TEST SEQUENCE **Test Group** Test Item F В С D Е G А Н L J Κ Examination of Product 15 14 15 14 14 16 14 14 13 13 13 Low-signal Level Contact Resistance 2 25 26 25 25 27 25 25 Insulation Resistance 3 38 4 **Dielectric Withstanding Voltage** 49 Mating / Unmating Forces 3 Durability 3 Vibration 4 Mechanical Shock 3 Humidity 3 Salt Spray 5 Temperature Life 3 Temperature Rise 3 Thermal Shock 4 2 Solderability Resistance to Reflow Soldering Heat 2 Resistance to Hand Soldering Heat 2



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| Revision details :- | | | | | | | |
|---------------------|---|------|--------------|--|--|--|--|
| Revision | Information | Page | Release Date | | | | |
| A | Specification released. | - | 16/11/11 | | | | |
| В | Specification revision. | - | 04/07/12 | | | | |
| С | Thermal Shock & Mating/Umating Additional Info. | 3, 4 | 10/06/13 | | | | |

